



Product Change Notification

104146 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 104146 - 00
Change Title: Intel 56LD TSOP and 48LD TSOP Package
JEDEC Tray Transport Media Change, PCN
104146-00, FYI
Date of Publication: June 04, 2004

Type of Change Notification:
FYI - (For Your Information)

Key Characteristics of the Change:
Transport Media

Forecasted Key Milestones:

Date of Qualification Data Availability:	Jun 07, 2004
Date Customer Must be Ready to Receive Post-Conversion Material:	Jul 07, 2004
Date of First Availability of Post-Conversion Material:	Jul 07, 2004

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Intel 56LD TSOP and 48LD TSOP products currently shipped in JEDEC Tray shipping media (if applicable) that has been manufactured by 3M will add a new accredited supplier, Daewon. Daewon JEDEC tray design meets the design standards for TSOP Packages (Generic Matrix Tray For Shipping and Handling, JEDEC Standard No-95-1 Nov. 1997 Revision C).

Customer Impact of Change and Recommended Action:

There will be no change to the TSOP package sizes or materials and the product will continue to meet Intel's stringent quality requirements.

Change to the JEDEC (shipping media): All critical dimensions on the JEDEC tray meet the same form, fit and function as the current manufacturer. Device unit count will remain the same at 96 pockets per tray.

JEDEC tray part numbers added:

56LD TSOP: Daewon part number 124-1420-E19 equates to part number 21002-385-129 from 3M

48LD TSOP: Daewon part number 124-1220-E19 equates to part number 21002-392-129 from 3M

Customer's actions for the new JEDEC tray design are none to minimal. Dimensions on the new trays are identical on all key parameters, including pocket pitch, device orientation in the tray and the pocket seating depth. There are no anticipated changes to the customer pick and place equipment. The 3M and Daewon JEDEC trays will be shipped interchangeably.

Product Material Master Numbers will not be changed for device line items impacted by this new tray.

Products Affected / Intel Ordering Codes:

Component Product Table

Affected Product Code	Spec	Material Master #
E28F128J3A150 S L4AX	S L4AX	829335
E28F128J3A150 S L56K	S L56K	833866
E28F320J3A110 834996		834996
E28F320J3A110 S L5FS	S L5FS	835065
E28F320J5A120 832672		832672
E28F320J5A120 Q C56	Q C56	836522
E28F640J3A120 S L4AX	S L4AX	829867
E28F640J3A120 S L5AQ	S L5AQ	834162
RC28F128J3C120 Q X69	Q X69	859953
RC28F320J3C110 Q X81	Q X81	859971
RC28F640J3C115 Q X75	Q X75	859966
SLXT332QE.G2 832211		832211
SLXT350QE.A2 832244		832244
SLXT360QE.A2 832197		832197
SLXT361QE.A2 832199		832199
TE28F128J3C120 853313		853313
TE28F128J3C120 Q X72	Q X72	859949
TE28F128J3C120 S L75F	S L75F	854777
TE28F128J3C120 S L7GP	S L7GP	860760
TE28F128J3C150 848539		848539
TE28F128J3C150 S L758	S L758	854767
TE28F160B3BD70 853987		853987
TE28F160B3TA90 819076		819076
TE28F160B3TC70 843615		843615
TE28F160B3TD70 853991		853991
TE28F160C3BA110819307		819307
TE28F160C3BA90 819073		819073
TE28F160C3BC70 843616		843616
TE28F160C3BC90 852043		852043
TE28F160C3BD70 853988		853988
TE28F160C3BD90 853990		853990
TE28F160C3TA110819310		819310
TE28F160C3TA90 819078		819078
TE28F160C3TD70 853932		853932
TE28F160C3TD90 853993		853993

Affected Product Code	Spec	Material Master #
TE28F160F3T95 822875		822875
TE28F160S375 819621		819621
TE28F256J3C125 S L7JQ	S L7JQ	861000
TE28F320B3BC70 833385		833385
TE28F320B3BC90 833379		833379
TE28F320B3BD70 856552		856552
TE28F320B3BD90 855789		855789
TE28F320B3TD70 856550		856550
TE28F320B3TD90 856553		856553
TE28F320C3BA110820967		820967
TE28F320C3BC70 833387		833387
TE28F320C3BC90 833377		833377
TE28F320C3BD70 855810		855810
TE28F320C3BD90 855786		855786
TE28F320C3TC70 833388		833388
TE28F320C3TC90 833376		833376
TE28F320C3TD70 855788		855788
TE28F320C3TD90 855787		855787
TE28F320J3C110 856508		856508
TE28F320J3C110 Q X84	Q X84	859973
TE28F320J3C110 S L7GW	S L7GW	860765
TE28F640C3BC80 851209		851209
TE28F640C3TC80 851245		851245
TE28F640J3C115 853422		853422
TE28F640J3C115 Q X78	Q X78	859968
TE28F640J3C115 S L7GY	S L7GY	860771
TE28F640J3C120 853315		853315
TE28F800F3T95 823648		823648

Reference Documents / Attachments:

Document:

TSOP Package Information

Location #:

<http://developer.intel.com/design/flcomp/packdata/296514.htm>

PCN Revision History:

Date of Revision:

June 4, 2004

Revision Number:

00

Reason:

Originally Published PCN